

2.7 V to 5.5 V Input, 20 A

Driver MOSFET IC for Automotive

BD96340MFF-C

General Description

BD96340MFF-C is a Driver MOSFET IC which supports up to 20 A continuous output current.

Features

- AEC-Q100 Qualified^(Note 1)
- Functional Safety Supportive Automotive Products
- Built-in Up to 20 A Continuous Output Current and 30 A Peak Output Current Ability MOSFETs.
- Built-in Protection. OCP (Over Current Protection), TSD (Thermal Shutdown)
- Built-in UVLO (Under Voltage Lockout), OVLO (Over Voltage Lockout)
(Note 1) Grade1

Applications

- Advanced Driver Assistance Systems (ADAS)
- Instrument Cluster Panel
- In-vehicle Infotainment Systems (IVI Systems)

Key Specifications

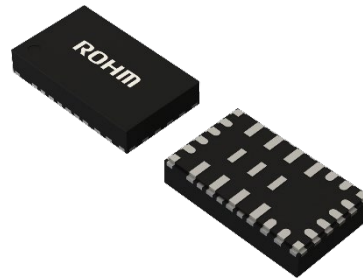
- Input Voltage Range: 2.7 V to 5.5 V
- Continuous Output Current: 20 A (Max)
- Peak Output Current: 30 A (Max)
- Shutdown Current: 0 μA (Typ)
- Operating Ambient Temperature Range: -40 °C to +125 °C

Packages

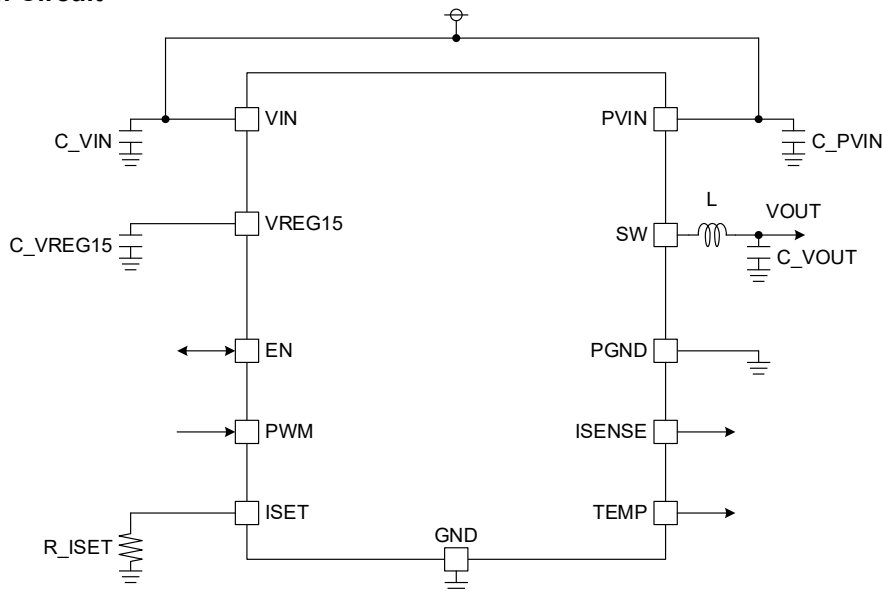
VFN27FV5030

W (Typ) x D (Typ) x H (Max)

5.0 mm x 3.0 mm x 1.0 mm



Typical Application Circuit



○Product structure : Silicon integrated circuit ○This product has no designed protection against radioactive rays.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition. However, pins that drive inductive loads (e.g. motor driver outputs, DC-DC converter outputs) may inevitably go below ground due to back EMF or electromotive force. In such cases, the user should make sure that such voltages going below ground will not cause the IC and the system to malfunction by examining carefully all relevant factors and conditions such as motor characteristics, supply voltage, operating frequency and PCB wiring to name a few.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

8. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

9. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

10. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When $GND > Pin A$ and $GND > Pin B$, the P-N junction operates as a parasitic diode.
When $GND > Pin B$, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

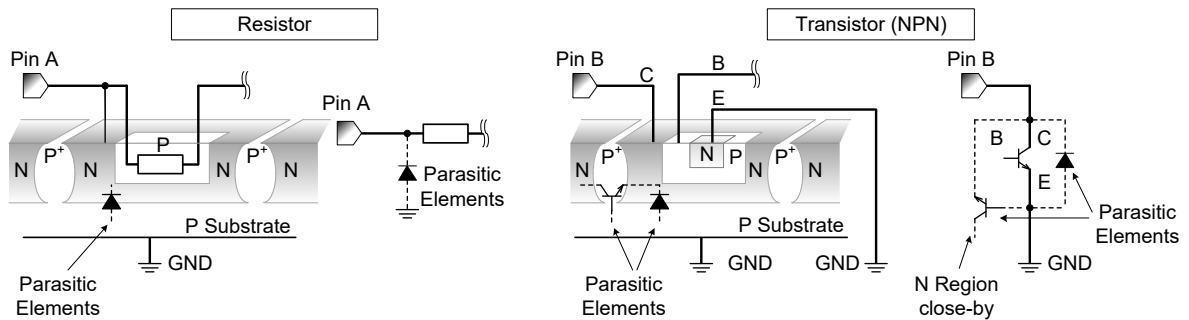


Figure 1. Example of Monolithic IC Structure

11. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

12. Thermal Shutdown Circuit (TSD)

This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's maximum junction temperature rating. If however the rating is exceeded for a continued period, the junction temperature (T_j) will rise which will activate the TSD circuit that will turn OFF power output pins. The IC should be powered down and turned ON again to resume normal operation because the TSD circuit keeps the outputs at the OFF state even if the T_j falls below the TSD threshold.

Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

13. Over Current Protection Circuit (OCP)

This IC incorporates an integrated overcurrent protection circuit that is activated when the load is shorted. This protection circuit is effective in preventing damage due to sudden and unexpected incidents. However, the IC should not be used in applications characterized by continuous operation or transitioning of the protection circuit.

14. Functional Safety

"ISO 26262 Process Compliant to Support ASIL-***"

A product that has been developed based on an ISO 26262 design process compliant to the ASIL level described in the datasheet.

"Safety Mechanism is Implemented to Support Functional Safety (ASIL-*)"

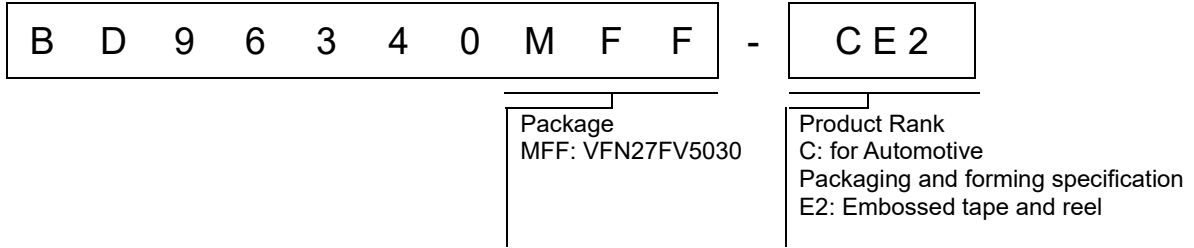
A product that has implemented safety mechanism to meet ASIL level requirements described in the datasheet.

"Functional Safety Supportive Automotive Products"

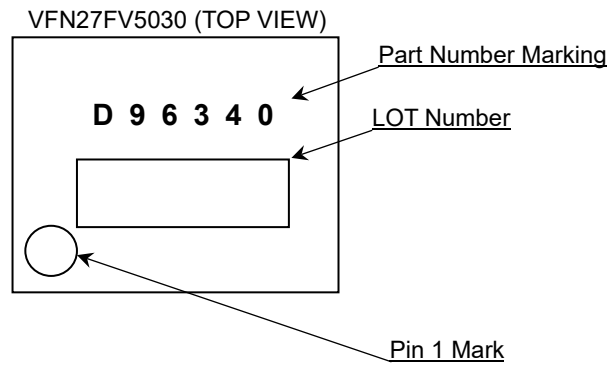
A product that has been developed for automotive use and is capable of supporting safety analysis with regard to the functional safety.

Note: "ASIL-***" is stands for the ratings of "ASIL-A", "-B", "-C" or "-D" specified by each product's datasheet.

Ordering Information



Marking Diagram



Revision History

Date	Revision	Changes
9. Mar. 2026	001	New Release

General Precaution

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